

Amendments to the Claims:

This listing of claims will replace all prior version and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) A method of processing a workpiece, the method comprising the steps of:
fastening a workpiece (52) to be processed to a work carrier by means of a solid,
wherein the work carrier comprises a porous material including a plurality of pores at least a portion of which are interconnected.
2. (Previously presented) The method as claimed in claim 1, wherein the work carrier comprises a gas-permeable work carrier.
3. (Currently amended) The method as claimed in claim 1 or 2, wherein the solid functions to separate for separating the workpiece and the work carrier, wherein the workpiece is released by means of a solvent.
4. (Previously presented) The method as claimed in claim 3, wherein a work carrier which is permeable to said solvent is used.
5. (Currently Amended) The method as claimed in claim 1, wherein the porous material is a ceramic, a glass, a glass ceramic, a metal, ~~in particular a sintered metal, a metal ceramic or a sintered material~~.
6. (Currently Amended) The method as claimed in ~~one of the preceding claims~~ claim 1, wherein the workpiece is thinned on the work carrier.
7. (Currently Amended) The method as claimed in claim 1, wherein the solid comprises a material selected from a group consisting of: wax, adhesive, a plastic material, or a double-sided adhesive tape.

8. (Currently Amended) The method as claimed in claim 1 ~~one of the preceding claims~~, wherein the workpiece contains a semiconductor material.

9. (Currently amended) The method as claimed in claim 1, wherein the solid fills at least a portion of an intermediate space between the workpiece and the work carrier.

10. (Currently Amended) A work carrier for processing a workpiece, said work carrier comprising a porous material including a plurality of pores at least a portion of which are interconnected.

11. (Currently Amended) The work carrier as claimed in claim 10, wherein the diameter (~~DM1~~) of the work carrier is equal to the diameter of the semiconductor wafer.

12. (Previously presented) The method as claimed in claim 1 wherein a vacuum is generated at the work carrier for the fastening.

13. (Previously presented) The method as claimed in claim 12 wherein the vacuum is generated after the application of the solid in liquefied form and before the hardening of the solid.

14. (Currently amended) The method of claim 4 wherein, to separate the workpiece and work carrier, said solvent penetrates into passages from a pore or from a the plurality of pores through the work carrier up to the solid.

15. (Previously presented) The method of claim 14 wherein the reparations of the workpiece from the work carrier preferably comprises reparation by the generation of a positive pressure on a side of the work carrier which is remote from the workpiece.

16. (Currently amended) The method as claimed in claim 1, wherein the average pore size has a value of between 20 μ m and 500 μ m ~~or between 50 μ m and 400 μ m~~, and/or wherein the porosity of the porous material has a value of between 20% and 50%.

17. (Currently amended) The method as claimed in claim 1, wherein the value of the open porosity of the porous material lies between 10% and 60% ~~or between 20% and 50%.~~

18. (Currently amended) The method as claimed in claim 1, wherein a portion of the plurality of pores include pore passages, wherein the pore passages comprise at least 10% ~~or at least 20%~~ of the pore volume belongs to pore passages (24, 26), and wherein the pore passage passing through traverse the porous material from a top side to a rear side of the carrier.

19. (Currently amended) The method as claimed in claim 1, wherein the porous material comprises a ceramic material manufactured according to one of German Institute Standard DIN 51056, 1985 or European Standard 623-2, 1992 ~~used is P65 or P55, and/or wherein the pores (14 to 22) are arranged irregularly and/or according to a uniform distribution.~~

20. (New) The method as claimed in claim 1, wherein the average pore size ranges from 50µm to 100µm.

21. (New) The method as claimed in claim 1, wherein the value of the open porosity of the porous material lies between 20% and 50%.

22. (New) The work carrier as claimed in claim 10, wherein the plurality of pores comprise a branched pore network within the work carrier.

23. (New) The work carrier as claimed in claim 10, wherein a portion of the plurality of pores include pore passages, wherein the pore passages comprise at least 10% of the pore volume, and wherein the pore passages traverse the work carrier from a top side to a rear side of the work carrier.